MA24D60

Silicon epitaxial planar type

For rectification

■ Features

- Forward current (Average) $I_{F(AV)}$ = 2.0 A rectification is possible
- Low forward voltage V_F

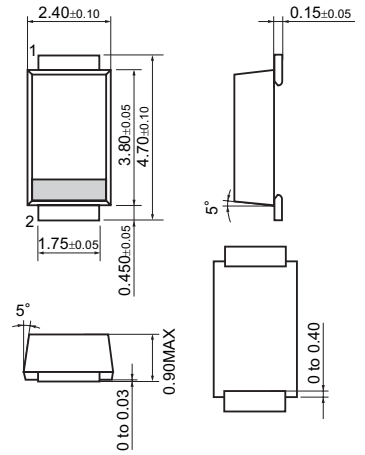
■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current (Average) *1	$I_{F(AV)}$	2.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	60	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–40 to +150	°C

Note) ∗1: Mounted on an alumina PC board

∗2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

Unit : mm



1 : Anode
2 : Cathode

TMiniP2-F1 Package

Marking Symbol: 5W

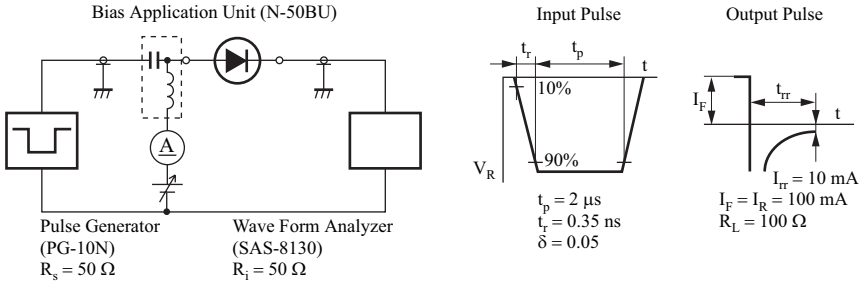
■ Electrical Characteristics T_a = 25°C±3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 2.0 A		0.43	0.48	V
Reverse current	I_R	V_R = 40 V		30	200	μA
Terminal capacitance	C_t	V_R = 10 V, f = 1 MHz		90		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 100 mA, I_{rr} = 10 mA, R_L = 100 Ω		30		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. ∗: t_{rr} measurement circuit



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